



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

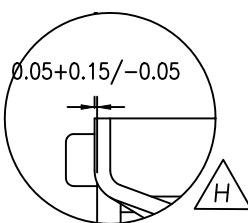
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

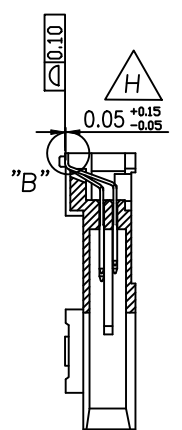
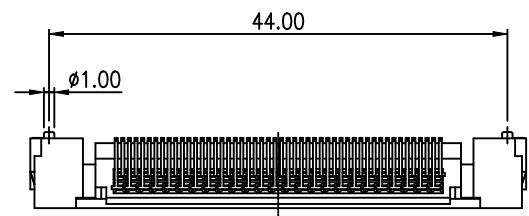
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



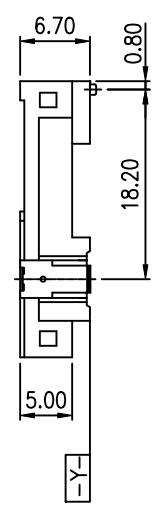
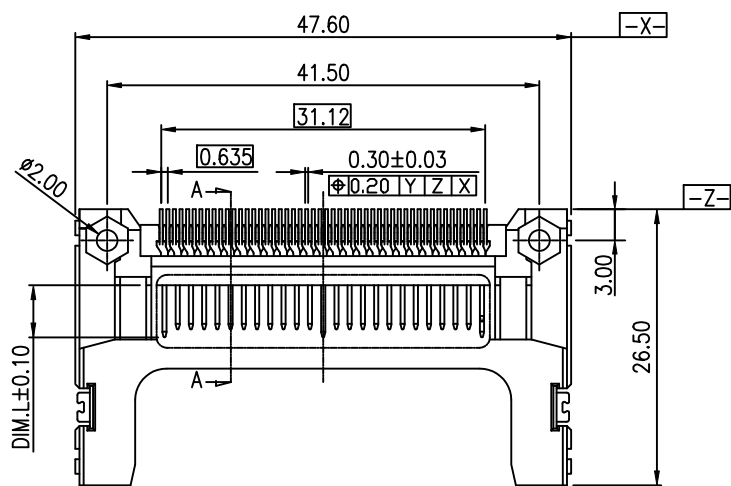
PRODUCT NO.
10017963-XXXXX



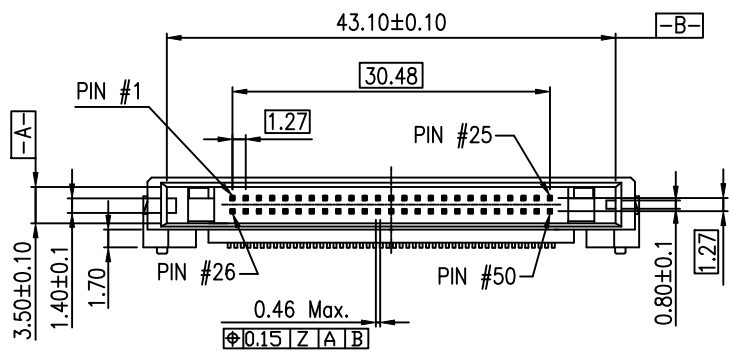
DETAIL B



SECTION A-A



PIN TYPE	DIM.L±0.10	PIN NUMBER
DETECT	3.50	25,26
CENERAL	4.25	ALL OTHER PINS
POWER	5.00	1,13,38,50



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ltr	ecn no	dr	date	linear	.X ± 0.30		projection	www.fciconnect.com		
C	T03-0415	J.C	9/22/03'		.XX ± 0.20			title	CF CARD HEADER TYPE 1	
D	T05-0122	A.C	6/07/05	angles	.XXX ± 0.10		MM		product family	code
E	T07-1119	WL	07/24/07		0° ±2°			scale		
F	T08-1014	WL	01/24/08	dr	JASON HSU	01/09/03'	A4		10017963	1 of 3
G	T08-1023	WL	02/12/08	engr	JASON HSU	01/09/03'				
H	T10-0056	S.LIN	10'-5-06	chr	STERLING LIN	01/09/03'				
				appd	JAMES HSU	01/09/03'				
sheet index	revision sheet	H	H	H						
		1	2	3						

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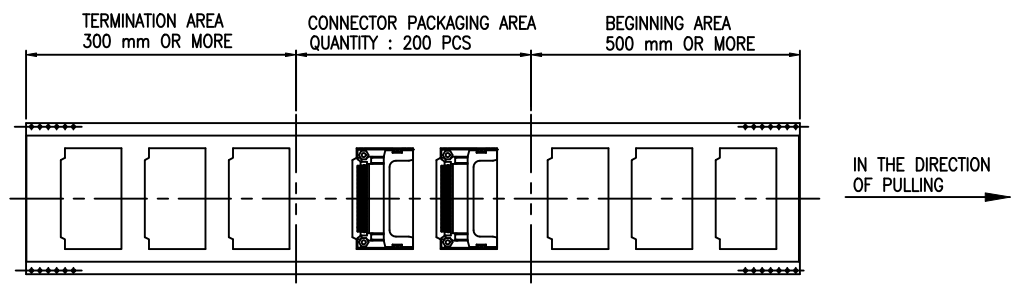
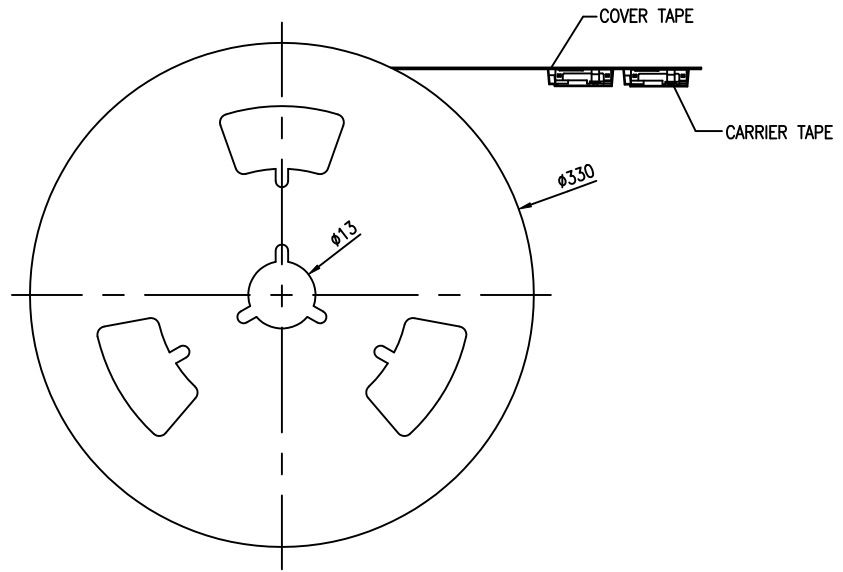
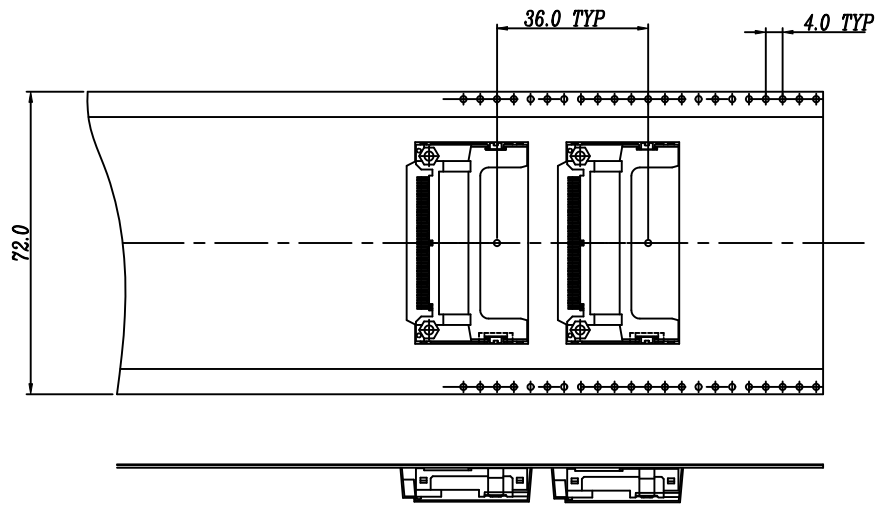
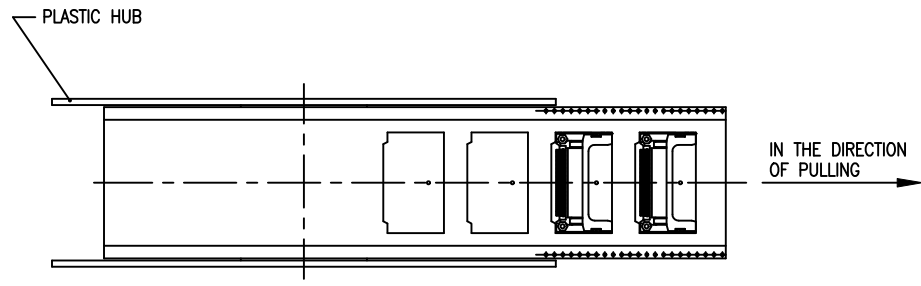


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1 | 2

3

4



COMPOSITION OF PACKAGING

NOTES:

1. CARRIER TAPE : PS , t=0.35mm.
2. COVER TAPE : PE.
3. PLASTIC HUB : PS.

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					.XXX ± 0.10						
				angles	0° ±2'		 MM	product family			code
				dr	JASON HSU	01/09/03'		size			TWN
				enrg	JASON HSU	01/09/03'		dwg no			sheet
				chr	STERLING LIN	01/09/03'		A4			2 of
				appd	JAMES HSU	01/09/03'		10017963			
sheet index	revision sheet						scale				

1 | 2

3

4

ACAD

PDM: Rev:H

STATUS: Released

cage code 22526
 Date: 09 May 2010

NOTES:

1. Materials:
 Housing: High Temperature Thermoplastic , UL94V-0, Color/Natural.
 Contact: Copper Alloy.
 Solderable Holddown: Copper Alloy.

2. Specification:
 Product Spec: GS-12-240.
 Packaging Spec: GS-14-1010.

3. Tin/Lead Plating Spec:
 Contact: Under Plated 50u" Min Nickel All Over,
 100u" Min Tin/Lead in Solder Tail Area,
 Selective Gold Plating in Contact Area.
 Solderable Holddown: Under Plated 50u" Min Nickel,
 Plated 100u"Min Tin/Lead All Over.

4. Lead-Free Plating Spec:
 Contact: Under Plated 50u" Min Nickel All Over,
 100u" Min Pure Matte Tin in Solder Tail Area,
 Selective Gold Plating in Contact Area.
 Solderable Holddown: Under Plated 50u" Min Nickel,
 Plated 100u"Min Pure Matte Tin All Over.

5. The Housing Will Withstand Exposure to 260°C Peak
 Temperature For 10 Seconds In A Convection, IR Or Vaper
 Phase Reflow Oven.

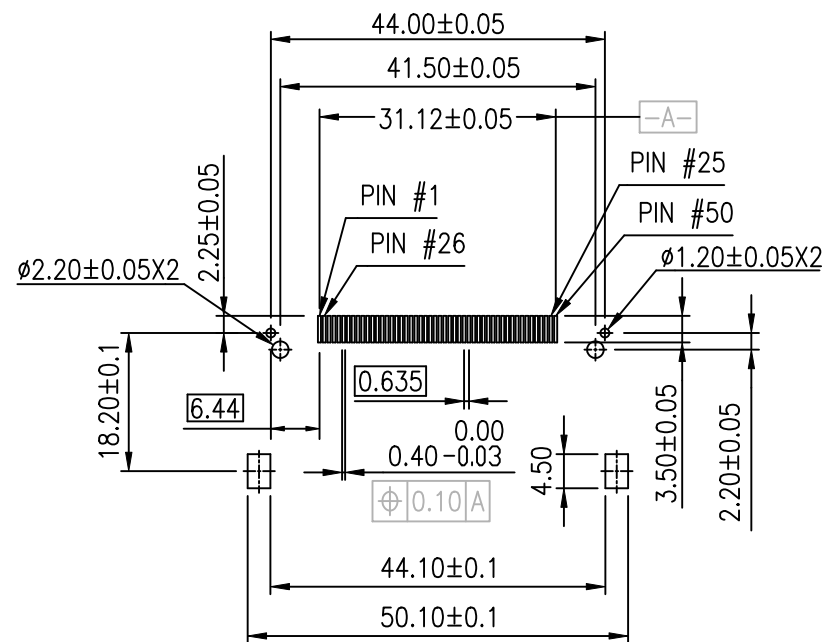
6. This Product (10017963-XXXXLX) Meets the European Union
 Directive as Described in GS-22-008, Sub Clause 3.1.
 (2002/95/EC).

7. PART NUMBER DESCRIPTION:
 10017963-X050XX

LEAD-FREE PLATING OPTION
 BLANK: TIN/LEAD PLATING(SEE NOTE3).
 LF: LEAD-FREE PLATING(SEE NOTE4).

PACKAGING
 BLANK: PVC TRAY.
 T: TAPE & REEL.

CONTACT AREA PLATING:
 D: 15u" GOLD.
 E: 30u" GOLD.



P.C.B Layout

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H					.XX ± 0.20					CF CARD HEADER TYPE 1	
					.XXX ± 0.10						
				angles	0° ± 2°				MM	product family	
				dr	JASON HSU	01/09/03'	scale			code	
				enrg	JASON HSU	01/09/03'	A4			TWN	
				chr	STERLING LIN	01/09/03'			sheet		
				appd	JAMES HSU	01/09/03'			3 of		
sheet index	revision sheet										